



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **TANIGUCHI, et al.**

Serial No.: 09/836,182

Group Art Unit: 2827

Filed: April 18, 2001

Examiner: MITCHELL, James M.

P.T.O. Confirmation No.: 7961

For: **METHOD OF FABRICATING SEMICONDUCTOR  
HAVING THROUGH HOLE**

**RESPONSE UNDER 37 CFR §1.116**  
**- EXPEDITED RESPONSE -**  
**GROUP ART UNIT 2827**

**BOX AF**

Commissioner for Patents  
Washington, D.C. 20231

November 22, 2002

Sir:

In response to the Office Action dated **August 13, 2002**, extended by one month by an extension of time filed herewith, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please amend Claim 14, as follows:

14. (Four Times Amended) A semiconductor device comprising a semiconductor chip, a tape for mounting said semiconductor chip thereto, an adhesive resin layer interposed between said semiconductor chip and said tape, and solder balls arranged on said tape, characterized in that said tape has no artificially produced vapor escape holes formed therein, and is of a material having high water permeability of  $10 \text{ g/m}^2 \cdot 24\text{H}$  or more, sufficient to prevent cracking and bulging of said

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semiconductor device which might occur when the solder balls are reflowed after said semiconductor device absorbs moisture.